



100% Material Declaration Data Sheet BFG957

PK185 (v1.0) September 21, 2006

Material Declaration Data Sheet

Average Weight: 18.0000 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0425830	2.366%
	Silicon	7440-21-3	100.00		0.425830	
Solder Bump					0.010000	0.056%
	Tin	7440-31-5	63.00		0.006300	
	Lead	7439-92-1	37.00		0.037000	
Underfill					0.071000	0.394%
	Silica	60676-86-0	70.00		0.049700	
	Epoxy Resin A	9003-36-5	20.00		0.014200	
	Epoxy Resin B	25068-38-6	3.00		0.002130	
	Hardener	19900-65-3	7.00		0.004970	
Heat Spreader					11.000000	61.111 %
	Copper	7440-50-8	98.00		10.780000	
	Chromium	7440-47-3	2.00		0.220000	
Heat Spreader Adhesive					0.085000	0.472%
	Silica and other filler materials	Proprietary	70.00		0.059500	
	Polymetric Resin		27.00		0.022950	
	Silane compound		3.00		0.002550	
Substrate					4.783460	26.575%
	Copper	7440-50-8	41.40	Metal Layer	1.980352	
	Nickel	7440-02-0	0.81	Metal Layer	0.038746	
	Gold	7440-57-5	0.18	Metal Layer	0.008610	
	Glass Fiber	N/A	4.17		0.199470	
	Halogen Fire Retardant	N/A	6.24		0.298488	
	BT (core)	N/A	33.30		1.592892	
	Solder Mask	N/A	13.90		0.664901	
Solder Balls					1.624710	9.026 %
	Tin	7440-31-5	95.50		1.551598	
	Ag	7440-02-0	4.00		0.064988	
	Copper	7440-50-8	0.50		0.008124	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
9/21/06	1.0	Initial release.